

Graphene Thermal pad

GSF110-030 is a novel thermal interface pad featuring high thermal conductivity and low thermal resistance. Utilizing graphene as the core thermal filler and employing oriented alignment and lamination-composite technologies, it establishes vertical thermal conduction pathways that significantly enhance heat transfer efficiency. It is suitable for high-power thermal management applications, such as base stations, automotive domain controllers, and high-performance computing chips. Additionally, the pad offers high resilience, excellent conformability, and resistance to deformation.

【Features】

- ▶ Ultra-high thermal conductivity: up to 110 W/(m·K);
- ▶ Low thermal resistance and low loss: extremely low interfacial thermal resistance, rapid and efficient heat transfer; High resilience: resilience $\geq 90\%$;
- ▶ Soft and easy to fit: excellent fit;
- ▶ High reliability: no pumping out.

【Product Advantages】

- ▶ **High Thermal Conductivity & Low Thermal Resistance:** 110 W/m·K thermal conductivity ensures efficient, directional heat transfer; it rapidly dissipates heat from the chip source, significantly enhancing equipment operational efficiency and stability.
- ▶ **Flexible & Easy to Install:** Soft and highly compressible, it conforms to various complex assembly surfaces to minimize contact thermal resistance; installation is convenient and causes no damage to components.
- ▶ **High Stability, Weather Resistance & Reliability:** Features a wide operating temperature range, low outgassing, and excellent aging resistance; performance remains undiminished under long-term full-load and thermal cycling conditions, ensuring stable, long-term equipment operation.

【Typical Applications】

- ▶ Semiconductor testing.
- ▶ AI chips.
- ▶ Intelligent driving chips.
- ▶ Optical modules.
- ▶ Communication equipment.
- ▶ Drones.
- ▶ Humanoid robots.

【Storage Conditions】

Store in a cool place.
Storage temperature: $\leq 30^{\circ}\text{C}$
Humidity: $\leq 75\%$

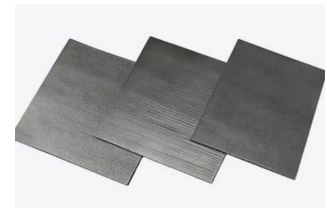
【Packaging】

Packaging customized according to customer requirements.

【Shelf Life】 The shelf life of this product is 12 months.

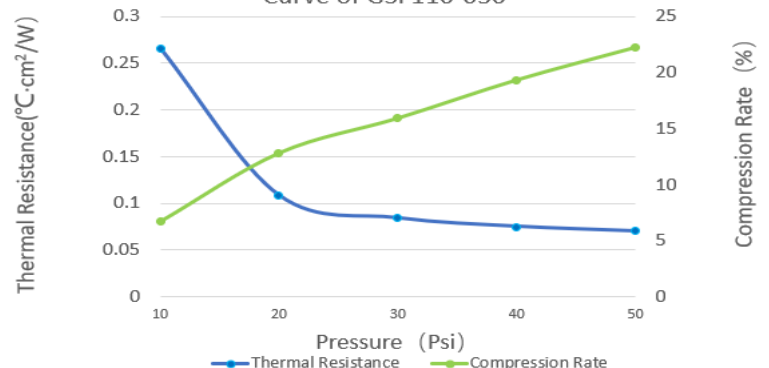
This product series is environmentally friendly and complies with RoHS 2.0, Halogen, and REACH standards.

【Product Illustrate】



Performance Type	Product Type	GSF110-030 (0.3mm)	Testing Standards
Thermal Properties	Thermal Conductivity (W/m·K)	110	ASTM E1461
	Thermal resistance ($^{\circ}\text{C}\cdot\text{cm}^2/\text{W}$, @50psi)	≤ 0.08	ASTM D5470
	Application Temperature ($^{\circ}\text{C}$)	-40~150	/
Physical Properties	Rebound rate (%)	≥ 90	/
	Tensile Strength (Mpa) (Orientation direction)	≥ 0.05	ASTM D412
	Color	Black	目视/Visual
	Thickness (mm)	0.2~2.0	ASTM D374
	Density (g/cm^3)	0.3~0.7	ASTM D792
	Oil Bleeding Rate (%)	≤ 3	/
Flame	Flammability	V-0	UL94

Pressure-Thermal Resistance & Compression Rate Curve of GSF110-030



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